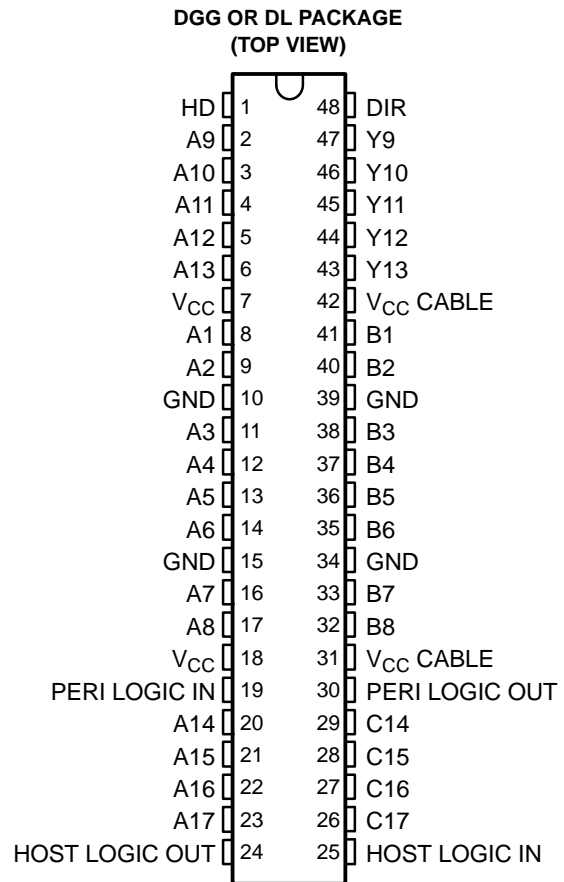


FEATURES

- **Auto-Power-Up Feature Prevents Printer Errors When Printer Is Turned On, But No Valid Signal Is at A9–A13 Pins**
- **1.4-k Ω Pullup Resistors Integrated on All Open-Drain Outputs Eliminate the Need for Discrete Resistors**
- **Designed for IEEE Std 1284-I (Level-1 Type) and IEEE Std 1284-II (Level-2 Type) Electrical Specifications**
- **Flow-Through Architecture Optimizes PCB Layout**
- **I_{off} and Power-Up 3-State Support Hot Insertion**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection**
 - ± 4 kV – Human-Body Model
 - ± 8 kV – IEC 61000-4-2, Contact Discharge (Connector Pins)
 - ± 15 kV – IEC 61000-4-2, Air-Gap Discharge (Connector Pins)
 - ± 15 kV – Human-Body Model (Connector Pins)



DESCRIPTION/ORDERING INFORMATION

The SN74LVCE161284 is designed for 3-V to 3.6-V V_{CC} operation. This device provides asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

This device has eight bidirectional bits; data can flow in the A-to-B direction when the direction-control input (DIR) is high and in the B-to-A direction when DIR is low. This device also has five drivers that drive the cable side and four receivers. The SN74LVCE161284 has one receiver dedicated to the HOST LOGIC line and a driver to drive the PERI LOGIC line.

ORDERING INFORMATION

| T _A | PACKAGE ⁽¹⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------------------|---------------|-----------------------|------------------|
| 0°C to 70°C | SSOP – DL | Tube | SN74LVCE161284DL | LVCE161284 |
| | | Tape and reel | SN74LVCE161284DLR | |
| | TSSOP – DGG | Tape and reel | SN74LVCE161284DGGR | LVCE161284 |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74LVCE161284
19-BIT IEEE STD 1284 TRANSLATION TRANSCEIVER
WITH ERROR-FREE POWER UP



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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The output drive mode is determined by the high-drive (HD) control pin. When HD is high, the outputs are in a totem-pole configuration, and in an open-drain configuration when HD is low. This meets the drive requirements as specified in the IEEE Std 1284-I (level-1 type) and IEEE Std 1284-II (level-2 type) parallel peripheral-interface specifications. Except for HOST LOGIC IN and peripheral logic out (PERI LOGIC OUT), all cable-side pins have a 1.4-kΩ integrated pullup resistor. The pullup resistor is switched off if the associated output driver is in the low state or if the output voltage is above V_{CC} CABLE. If V_{CC} CABLE is off, PERI LOGIC OUT is set to low.

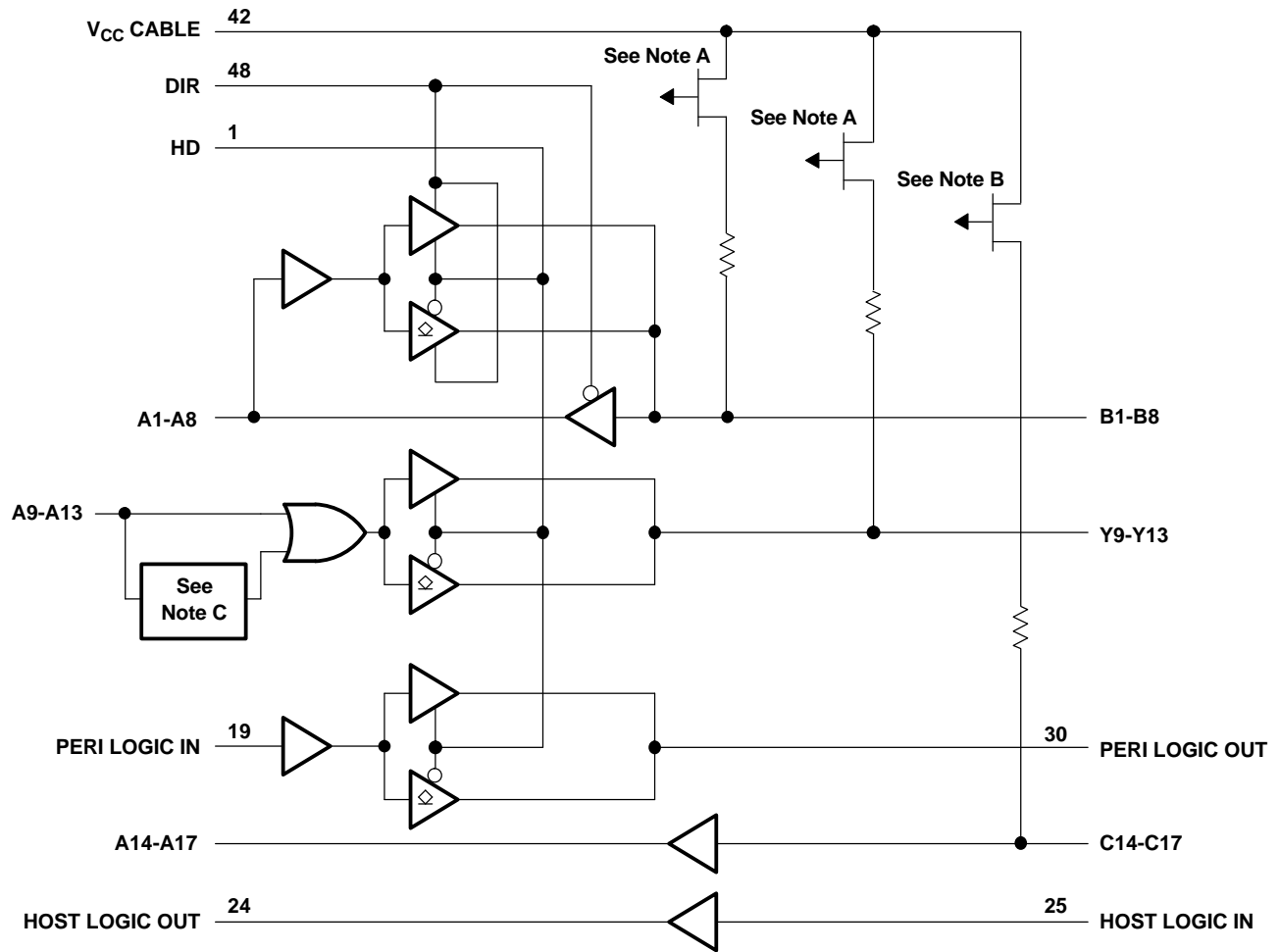
The device has two supply voltages. V_{CC} is designed for 3-V to 3.6-V operation. V_{CC} CABLE supplies the inputs and output buffers of the cable side only and is designed for 3-V to 3.6-V and for 4.7-V to 5.5-V operation. Even when V_{CC} CABLE is 3 V to 3.6 V, the cable-side I/O pins are 5-V tolerant.

The Y outputs (Y9–Y13) stay in the high state after power on until an associated input (A9–A13) goes high. When an associated input goes high, all Y outputs are activated, and noninverting signals of the associated inputs are driven through Y outputs. This special feature prevents printer-system errors caused by deasserting the BUSY signal in the cable at power on.

FUNCTION TABLE

| INPUTS | | OUTPUT | MODE |
|--------|----|------------|---|
| DIR | HD | | |
| L | L | Open drain | A9–A13 to Y9–Y13 and PERI LOGIC IN to PERI LOGIC OUT |
| | | Totem pole | B1–B8 to A1–A8 and C14–C17 to A14–A17 |
| L | H | Totem pole | B1–B8 to A1–A8, A9–A13 to Y9–Y13, PERI LOGIC IN to PERI LOGIC OUT, and C14–C17 to A14–A17 |
| H | L | Open drain | A1–A8 to B1–B8, A9–A13 to Y9–Y13, and PERI LOGIC IN to PERI LOGIC OUT |
| | | Totem pole | C14–C17 to A14–A17 |
| H | H | Totem pole | A1–A8 to B1–B8, A9–A13 to Y9–Y13, C14–C17 to A14–A17, and PERI LOGIC IN to PERI LOGIC OUT |

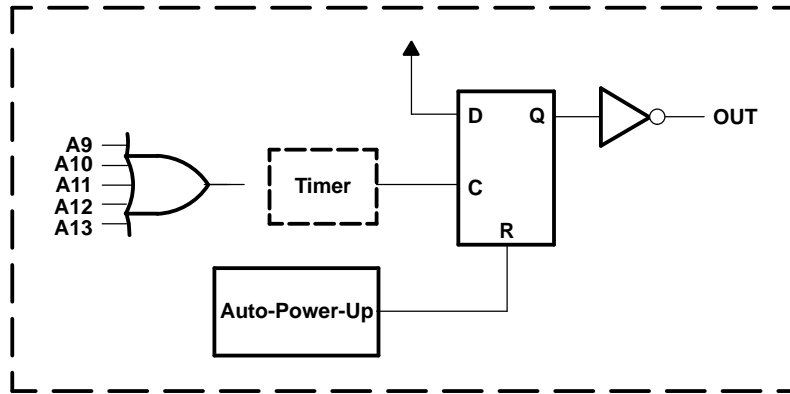
LOGIC DIAGRAM



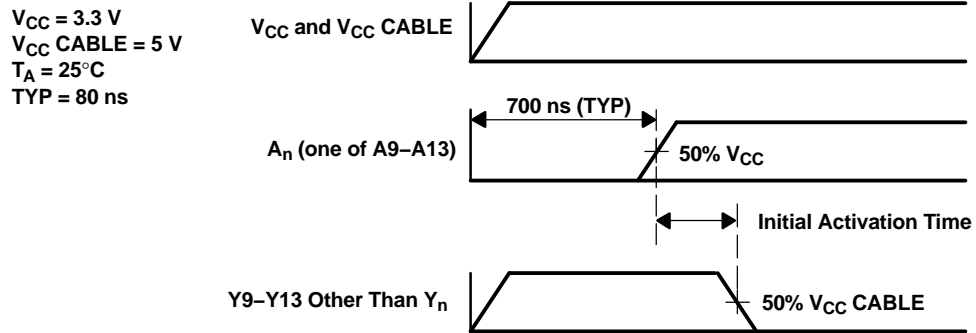
- NOTES: A. The PMOS transistors prevent backdriving current from the signal pins to V_{CC} CABLE when V_{CC} CABLE is open or at GND. The PMOS transistor is turned off when the associated driver is in the low state.
- B. The PMOS transistor prevents backdriving current from the signal pins to V_{CC} CABLE when V_{CC} CABLE is open or at GND.
- C. Active input detection circuit forces Y9-Y13 to the high state after power-on, until one of the A9-A13 goes high (see Figure 1).

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Active Input Detection Circuit



NOTE A: One of A9–A13 is switched as shown above, and the other four inputs are forced to low state.

Figure 1. Error-Free Circuit Timing

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT | |
|---|--|---|------|----------------|---|
| $V_{CC\ CABLE}$ | Supply voltage range | -0.5 | 7 | V | |
| V_{CC} | Supply voltage range | -0.5 | 4.6 | V | |
| V_I , V_O | Input and output voltage range | Cable side ⁽²⁾⁽³⁾ | -2 | 7 | V |
| | | Peripheral side ⁽²⁾ | -0.5 | $V_{CC} + 0.5$ | V |
| I_{IK} | Input clamp current | $V_I < 0$ | -20 | mA | |
| I_{OK} | Output clamp current | $V_O < 0$ | -50 | mA | |
| I_O | Continuous output current | Except PERI LOGIC OUT | ±50 | mA | |
| | | PERI LOGIC OUT | ±100 | mA | |
| Continuous current through each V_{CC} or GND | | | ±200 | mA | |
| I_{SK} | Output high sink current | $V_O = 5.5\ V$ and $V_{CC\ CABLE} = 3\ V$ | 65 | mA | |
| θ_{JA} | Package thermal impedance ⁽⁴⁾ | DGG package | 70 | °C/W | |
| | | DL package | 63 | | |
| T_{stg} | Storage temperature range | -65 | 150 | °C | |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The ac input-voltage pulse duration is limited to 40 ns if the amplitude is greater than -0.5 V.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

| | | MIN | MAX | UNIT | |
|-----------------|--|------------------------------|------|----------|---|
| $V_{CC\ CABLE}$ | Supply voltage for the cable side, $V_{CC\ CABLE} \geq V_{CC}$ | 3 | 5.5 | V | |
| V_{CC} | Supply voltage | 3 | 3.6 | V | |
| V_{IH} | High-level input voltage | A, B, DIR, and HD | 2 | V | |
| | | C14–C17 | 2.3 | | |
| | | HOST LOGIC IN | 2.6 | | |
| | | PERI LOGIC IN | 2 | | |
| V_{IL} | Low-level input voltage | A, B, DIR, and HD | 0.8 | V | |
| | | C14–C17 | 0.8 | | |
| | | HOST LOGIC IN | 1.6 | | |
| | | PERI LOGIC IN | 0.8 | | |
| V_I | Input voltage | Peripheral side | 0 | V_{CC} | V |
| | | Cable side | 0 | 5.5 | |
| V_O | Open-drain output voltage | HD low | 0 | 5.5 | V |
| I_{OH} | High-level output current | HD high, B and Y outputs | -14 | mA | |
| | | A outputs and HOST LOGIC OUT | -4 | | |
| | | PERI LOGIC OUT | -0.5 | | |
| I_{OL} | Low-level output current | B and Y outputs | 14 | mA | |
| | | A outputs and HOST LOGIC OUT | 4 | | |
| | | PERI LOGIC OUT | 84 | | |
| T_A | Operating free-air temperature | 0 | 70 | °C | |

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74LVCE161284
19-BIT IEEE STD 1284 TRANSLATION TRANSCEIVER
WITH ERROR-FREE POWER UP



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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | V _{CC} CABLE | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|---|--|---|---------------------------|---------------------------|---|--------------------|-----|------------|
| ΔV_t Hysteresis ($V_{T+} - V_{T-}$) | All inputs except the C inputs and HOST LOGIC IN | | 3.3 V | 5 V | 0.4 | | | V |
| | HOST LOGIC IN | | | | 0.2 | | | |
| | C inputs | | | | 0.8 | | | |
| V _{OH} | HD high, B and Y outputs | I _{OH} = -14 mA | 3 V | 3 V | 2.23 | | | V |
| | | | 3.3 V | 4.7 V | 2.4 | | | |
| | HD high, A outputs, and HOST LOGIC OUT | I _{OH} = -4 mA | 3 V | 3 V | 2.4 | | | |
| | | I _{OH} = -50 μ A | | | 2.8 | | | |
| | PERI LOGIC OUT | I _{OH} = -0.5 mA | 3.15 V | 3.15 V | 3.1 | | | |
| | | | 3.3 V | 4.7 V | 4.5 | | | |
| V _{OL} | B and Y outputs | I _{OL} = 14 mA | 3 V | 3 V | 0.77 | | | V |
| | A outputs and HOST LOGIC OUT | I _{OL} = 50 μ A | | | 0.2 | | | |
| | | I _{OL} = 4 mA | | | 0.4 | | | |
| | PERI LOGIC OUT | I _{OL} = 84 mA | | | 0.9 | | | |
| I _I | C inputs | V _I = V _{CC} | 3.6 V | 3.6 V | 50 | | | μ A |
| | | V _I = GND (pullup resistors) | | | -3.5 | | | |
| | All inputs except B or C inputs | V _I = V _{CC} or GND | | | 5.5 V | \pm 1 | | |
| I _{OZ} | A1–A8 | V _O = V _{CC} or GND | 3.6 V | 5.5 V | \pm 20 | | | μ A |
| | | V _O = V _{CC} CABLE | | | 50 | | | |
| | B outputs | V _O = GND (pullup resistors) | | 3.6 V | -3.5 | | | mA |
| | | Open-drain Y outputs | | | V _O = GND (pullup resistors) | -3.5 | | |
| I _{OZPU} | B and Y outputs | V _O = 5.5 V | 0 to 1.5 V ⁽²⁾ | 0 to 1.5 V ⁽²⁾ | 350 | | | μ A |
| | | V _O = GND | | | -5 | | | |
| I _{OZPD} | B and Y outputs | V _O = 5.5 V | 0 to 1.5 V ⁽²⁾ | 0 to 1.5 V ⁽²⁾ | 350 | | | μ A |
| | | V _O = GND | | | -5 | | | |
| I _{off} | Power-down input leakage, except A1–A8 or B1–B8 inputs | V _I or V _O = 0 to 3.6 V | 0 | 0 | 100 | | | μ A |
| | Power-down output leakage, B1–B8 and Y9–Y13 outputs | V _I or V _O = 0 to 5.5 V | | | 100 | | | |
| I _{CC} | | V _I = GND (12 \times pullup) | 3.6 V | 3.6 V | 45 | | | mA |
| | | | | 5.5 V | 70 | | | |
| | | V _I = V _{CC} , I _O = 0 | | 3.6 V | 0.8 | | | |
| Z _O | B1–B8, Y9–Y13 | I _{OH} = -35 mA | 3.3 V | 3.3 V | 36 | | | Ω |
| R pullup | B1–B8, Y9–Y13, C14–C17 | V _O = 0 V (in high-impedance state) | 3.3 V | 3.3 V | 1.15 | 1.65 | | k Ω |
| C _i | A9–A13, DIR, HD, PERI LOGIC IN | V _I = V _{CC} or GND | 3.3 V | 5 V | 6.5 | | | pF |
| | HOST LOGIC IN | | | | 4 | | | |
| C _{io} | A1–A8 | V _O = V _{CC} or GND | 3.3 V | 5 V | 8 | | | pF |
| | B1–B8 | | | | 13 | | | |

(1) Typical values are measured at T_A = 25°C.

(2) Connect the V_{CC} pin to the V_{CC} CABLE pin.

Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2 and Figure 3)

| PARAMETER | | FROM (INPUT) | TO (OUTPUT) | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|-----------------------------------|------------|--------------------------|-----------------------------------|------|--------------------|-----|------|
| t _{PLH} | Totem pole | A1–A8 | B1–B8 | 2 | | 30 | ns |
| t _{PHL} | | | | 2 | | 30 | |
| t _{PLH} | Totem pole | A9–A13 | Y9–Y13 | 2 | | 30 | ns |
| t _{PHL} | | | | 2 | | 30 | |
| t _{PLH} | Totem pole | B1–B8 | A1–A8 | 2 | | 12 | ns |
| t _{PHL} | | | | 2 | | 12 | |
| t _{PLH} | Totem pole | C14–C17 | A14–A17 | 2 | | 14 | ns |
| t _{PHL} | | | | 2 | | 14 | |
| t _{PLH} | Totem pole | PERI LOGIC IN | PERI LOGIC OUT | 2 | | 16 | ns |
| t _{PHL} | | | | 2 | | 16 | |
| t _{PLH} | Totem pole | HOST LOGIC IN | HOST LOGIC OUT | 1 | | 18 | ns |
| t _{PHL} | | | | 1 | | 18 | |
| t _{slew} | Totem pole | B1–B8 and Y9–Y13 outputs | | 0.05 | | 0.4 | V/ns |
| t _{PZH} | | HD | B1–B8, Y9–Y13, and PERI LOGIC OUT | 2 | | 30 | ns |
| t _{PHZ} | | | | 2 | | 25 | |
| t _{en} –t _{dis} | | DIR | A1–A8 | 2 | | 25 | ns |
| t _{PHZ} | | DIR | B1–B8 | 2 | | 25 | ns |
| t _{PLZ} | | | | 2 | | 25 | |
| t _r , t _f | Open drain | A1–A13 | B1–B8 or Y9–Y13 | 1 | | 120 | ns |
| t _{sk(o)} ⁽²⁾ | | A1–A8 or B1–B8 | B1–B8 or A1–A8 | | 3 | 10 | ns |

(1) Typical values are measured at V_{CC} = 3.3 V, V_{CC CABLE} = 5 V, and T_A = 25°C.

(2) Skew is measured at 1/2 (V_{OH} + V_{OL}) for signals switching in the same direction.

Table 1. ESD Protection

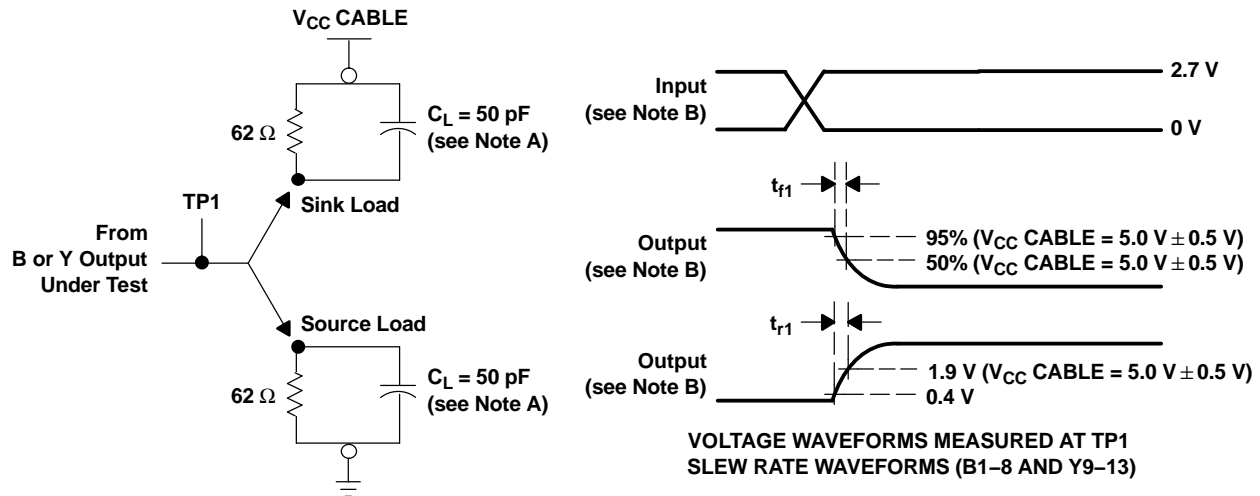
| PIN | TEST CONDITIONS | TYP | UNIT |
|--|----------------------------------|-----|------|
| B1–B8, Y9–Y13, PERI LOGIC OUT, C14–C17, HOST LOGIC IN | HBM | ±15 | kV |
| | Contact discharge, IEC 61000-4-2 | ±8 | |
| | Air-gap discharge, IEC 61000-4-2 | ±15 | |
| DIR, HD, A1–A8, A9–A13, PERI LOGIC IN, A14–A17, HOST LOGIC OUT | HBM | ±4 | kV |

Operating Characteristics

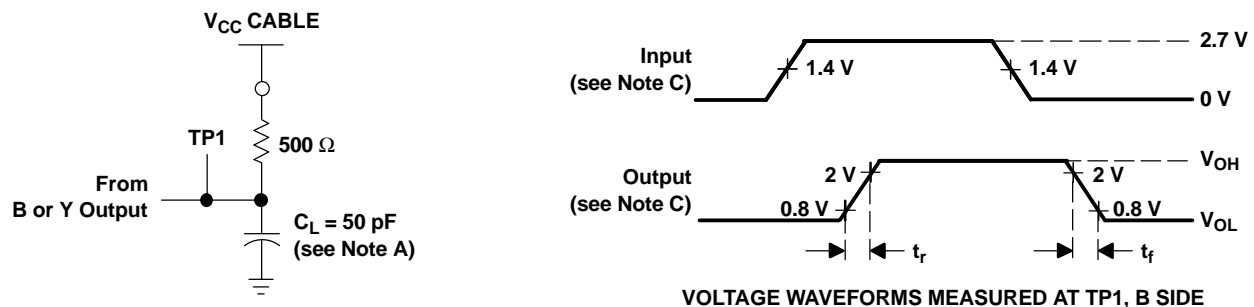
V_{CC} and V_{CC CABLE} = 3.3 V, C_L = 0, f = 10 MHz, T_A = 25°C

| PARAMETER | | FROM (INPUT) | TO (OUTPUT) | TYP | UNIT |
|-----------------|-------------------------------|---------------|----------------|-----|------|
| C _{pd} | Power dissipation capacitance | A | B | 15 | pF |
| | | A | Y | 6 | |
| | | PERI LOGIC IN | PERI LOGIC OUT | 10 | |
| | | B | A | 33 | |
| | | C | A | 29 | |
| | | HOST LOGIC IN | HOST LOGIC OUT | 29 | |

PARAMETER MEASUREMENT INFORMATION



SLEW RATE A-TO-B OR A-TO-Y LOAD (TOTEM POLE) OR PERI LOGIC IN TO PERI LOGIC OUT



A-TO-B LOAD OR A-TO-Y LOAD (OPEN DRAIN) OR PERI LOGIC IN TO PERI LOGIC OUT

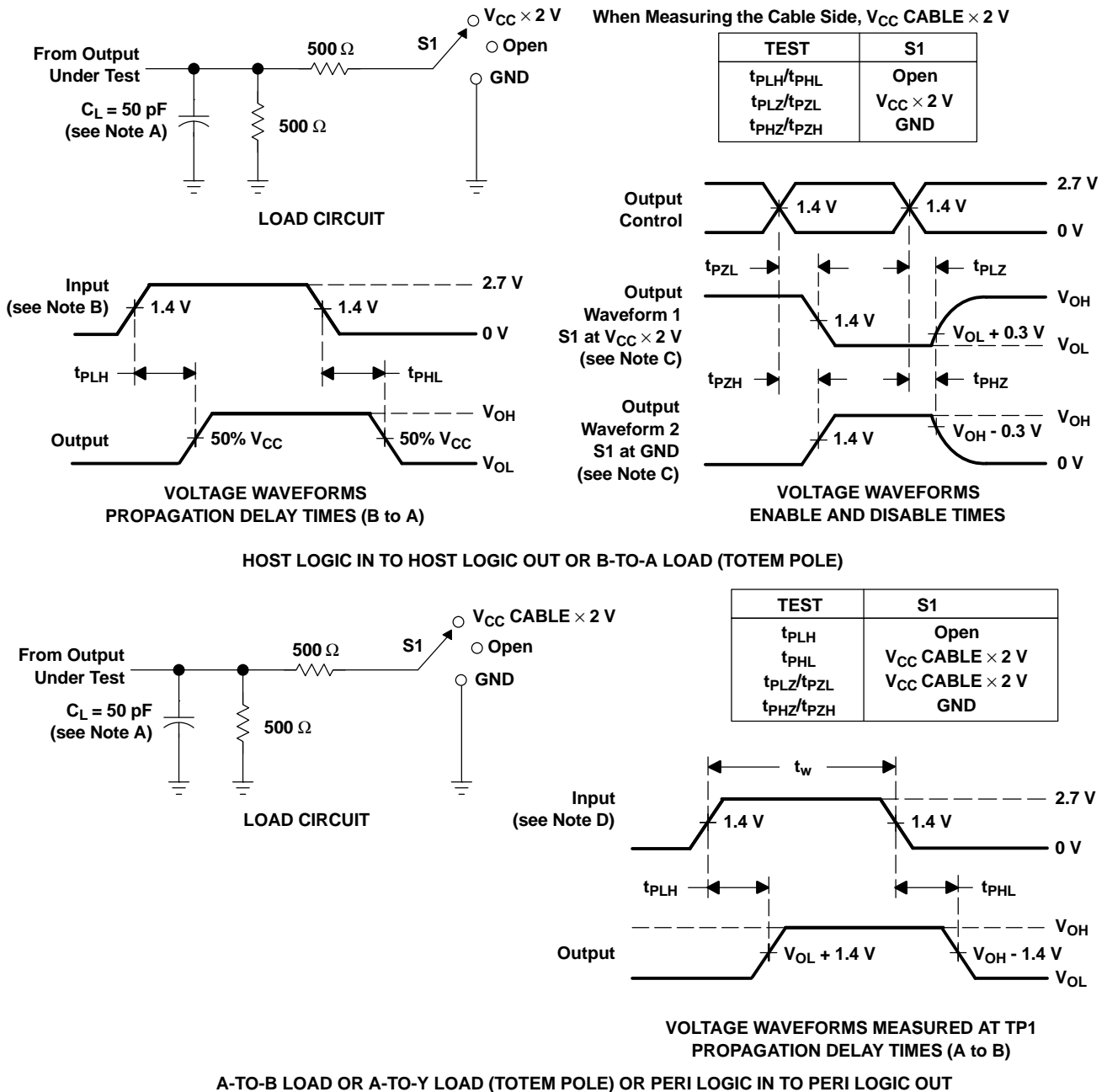
- NOTES: A. C_L includes probe and jig capacitance.
 B. When V_{CC} CABLE is 3.3 V ± 0.3 V, slew rate is measured between 0.4 V and 0.9 V for the rising edge and between 2.4 V and 1.9 V for the falling edge. When V_{CC} CABLE is 5 V ± 0.5 V, slew rate is measured between 0.4 V and 1.9 V for the rising edge and between 95% V_{CC} CABLE and 50% V_{CC} CABLE for the falling edge.

$$t_{\text{slew fall}} = V_{\text{CC}} \left(\frac{95\% - 50\%}{t_{f1}} \right) \quad t_{\text{slew rise}} = \left(\frac{1.9 \text{ V} - 0.4 \text{ V}}{t_{r1}} \right)$$

- C. Input rise (t_r) and fall (t_f) times are 3 ns. Rise and fall times (open drain) are <120 ns.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 F. t_{PZL} and t_{PZH} are the same as t_{en}.
 G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuits and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Input rise and fall times are 3 ns.
 - C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - D. Input rise and fall times are 3 ns. Pulse duration is $150 \text{ ns} < t_w < 10 \mu\text{s}$.
 - E. The outputs are measured one at a time, with one transition per measurement.
 - F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - G. t_{PZL} and t_{PZH} are the same as t_{en} .
 - H. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|--------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 74LVCE161284DGGRE4 | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74LVCE161284DGGRG4 | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74LVCE161284DLG4 | ACTIVE | SSOP | DL | 48 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74LVCE161284DLRG4 | ACTIVE | SSOP | DL | 48 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74LVCE161284VRE4 | ACTIVE | TVSOP | DGV | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74LVCE161284VRG4 | ACTIVE | TVSOP | DGV | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LVCE161284DGGR | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LVCE161284DL | ACTIVE | SSOP | DL | 48 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LVCE161284DLR | ACTIVE | SSOP | DL | 48 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LVCE161284VR | ACTIVE | TVSOP | DGV | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVCE161284DGGR | TSSOP | DGG | 48 | 2000 | 330.0 | 24.4 | 8.6 | 15.8 | 1.8 | 12.0 | 24.0 | Q1 |
| SN74LVCE161284DLR | SSOP | DL | 48 | 1000 | 330.0 | 32.4 | 11.35 | 16.2 | 3.1 | 16.0 | 32.0 | Q1 |
| SN74LVCE161284VR | TVSOP | DGV | 48 | 2000 | 330.0 | 16.4 | 7.1 | 10.2 | 1.6 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVCE161284DGGR | TSSOP | DGG | 48 | 2000 | 346.0 | 346.0 | 41.0 |
| SN74LVCE161284DLR | SSOP | DL | 48 | 1000 | 346.0 | 346.0 | 49.0 |
| SN74LVCE161284VR | TVSOP | DGV | 48 | 2000 | 346.0 | 346.0 | 33.0 |

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

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